

Title (en)  
ENCAPSULATION OF ORGANIC ELECTRONIC DEVICES

Title (de)  
VERKAPSELUNG FÜR ORGANISCHE ELEKTRONISCHE ANLAGE

Title (fr)  
ENCAPSULATION DE DISPOSITIFS ELECTRONIQUES ORGANIQUES

Publication  
**EP 1208726 A1 20020529 (EN)**

Application  
**EP 00957945 A 20000901**

Priority  
• US 0024126 W 20000901  
• US 15253699 P 19990903

Abstract (en)  
[origin: WO0119142A1] An electronic device configuration that prevents ambient moisture and oxygen from reacting with materials used in the fabrication of the devices and thus prevents ambient moisture and oxygen from deleteriously affecting device performance by use of an airtight enclosure comprising a porous drying agent.

IPC 1-7  
**H05B 33/04**; **H01L 51/20**

IPC 8 full level  
**H01L 51/50** (2006.01); **H01L 51/52** (2006.01); **H05B 33/04** (2006.01)

CPC (source: EP KR)  
**H05B 33/04** (2013.01 - EP KR); **H10K 50/842** (2023.02 - EP KR); **H10K 50/846** (2023.02 - EP KR); **H01L 2224/73265** (2013.01 - EP);  
**H01L 2924/16195** (2013.01 - EP)

Cited by  
CN104910366A

Designated contracting state (EPC)  
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)  
**WO 0119142 A1 20010315**; CA 2381230 A1 20010315; CN 1385053 A 20021211; EP 1208726 A1 20020529; JP 2003508891 A 20030304;  
KR 20020066321 A 20020814; TW 508970 B 20021101

DOCDB simple family (application)  
**US 0024126 W 20000901**; CA 2381230 A 20000901; CN 00815087 A 20000901; EP 00957945 A 20000901; JP 2001522203 A 20000901;  
KR 20027002839 A 20020302; TW 89117977 A 20000915